

Listing of Claims:

1. (PREVIOUSLY PRESENTED) A bonded structure, comprising:
 - an integrated circuit element having input/output pads;
 - a substrate having input/output pads; and
 - a plurality of physical and electrical connections between said integrated circuit element input/output pads and said substrate input/output pads wherein each said connection includes a composite bump comprised of a polymer body and a conductive metal coating covering said polymer body, said polymer body has a Young's Modulus of between about 400,000 and 500,000 pounds per square inch, and wherein said composite bump is deformed when said connection is formed.
2. (ORIGINAL) The bonded structure of claim 1 wherein said polymer is polyamic acid polyimide.
3. (PREVIOUSLY PRESENTED) The bonded structure of claim 1 wherein said conductive metal coating comprises chrome, copper, and gold.
4. (ORIGINAL) The bonded structure of claim 1 wherein said composite bumps are formed on said integrated circuit element input/output pads prior to formation of said connection.

5. (ORIGINAL) The bonded structure of claim 1 wherein said composite bumps are formed on said substrate input/output pads prior to formation of said connection.

6. (CURRENTLY AMENDED) A The bonded structure of claim 1 wherein, comprising:

an integrated circuit element having input/output pads;

a substrate having input/output pads; and

a plurality of physical and electrical connections between said integrated circuit element input/output pads and said substrate input/output pads wherein each said connection includes composite bumps comprised of a polymer body and a conductive metal coating covering said polymer body, said composite bumps are formed on both said integrated circuit element input/output pads and said substrate input/output pads prior to formation of said connection, said polymer body has a Young's Modulus of between about 400,000 and 500,000 pounds per square inch, and said composite bumps are deformed when said connection is formed.

7-20. CANCELLED

21. (NEW) The bonded structure of claim 6 wherein said polymer is polyamic acid polyimide.

22. (NEW) The bonded structure of claim 6 wherein said conductive metal coating comprises chrome, copper, and gold.